imall

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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





BFP520F

Low Noise Silicon Bipolar RF Transistor

- For highest gain and low noise amplifier
 Outstanding Gms = 22.5 dB at 1.8 GHz
 Minimum noise figure NF_{min} = 0.95 dB at 1.8 GHz
- For oscillators up to 15 GHz
- Transition frequency $f_{\rm T}$ = 45 GHz
- Pb-free (RoHS compliant) and halogen-free thin small flat package with visible leads
- Qualification report according to AEC-Q101 available



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration				Package		
BFP520F	APs	1=B	2=E	3=C	4=E	-	-	TSFP-4

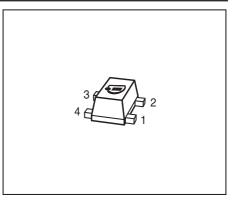
Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V _{CEO}		V
<i>T</i> _A = 25 °C		2.5	
<i>T</i> _A = -55 °C		2.4	
Collector-emitter voltage	V _{CES}	10	
Collector-base voltage	V _{CBO}	10	
Emitter-base voltage	V _{EBO}	1	
Collector current	Ι _C	50	mA
Base current	I _B	5	
Total power dissipation ¹⁾	P _{tot}	120	mW
<i>T</i> _S ≤ 98 °C			
Junction temperature	TJ	150	°C
Storage temperature	T _{Stg}	-55 150	

 $^{1}\mathcal{T}_{S}$ is measured on the emitter lead at the soldering point to pcb

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	430	K/W





Parameter	Symbol	Values			Unit
		min.	typ.	max.	1
DC Characteristics	·			•	
Collector-emitter breakdown voltage	V _{(BR)CEO}	2.5	3	3.5	V
I _C = 1 mA, I _B = 0					
Collector-emitter cutoff current	I _{CES}	-	-	10	μA
<i>V</i> _{CE} = 10 V, <i>V</i> _{BE} = 0					
Collector-base cutoff current	I _{CBO}	-	-	200	mA
$V_{\rm CB} = 5 \text{ V}, I_{\rm E} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	35	μA
V _{EB} = 1 V, <i>I</i> _C = 0					
DC current gain	h _{FE}	70	110	170	-
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 2 V, pulse measured					

Electrical Characteristics at T_A = 25 °C, unless otherwise specified

¹For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)



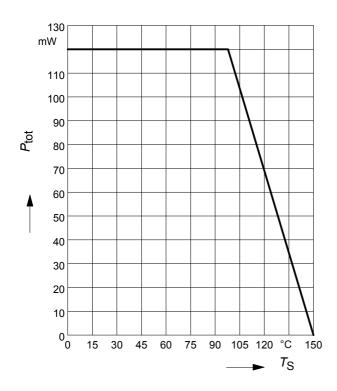
Parameter	Symbol		Values	•	Unit
		min.	typ.	max.	
AC Characteristics (verified by random samplin	<u>g)</u>				T
Transition frequency	f _T	32	45	-	GHz
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 2 V, f = 2 GHz					
Collector-base capacitance	C _{cb}	-	0.07	0.14	pF
$V_{\rm CB} = 2 \text{ V}, f = 1 \text{ MHz}, V_{\rm BE} = 0$,					
emitter grounded					
Collector emitter capacitance	C _{ce}	-	0.25	-	
$V_{CE} = 2 V, f = 1 MHz, V_{BE} = 0$,					
base grounded					
Emitter-base capacitance	C _{eb}	-	0.31	-	
$V_{\rm EB}$ = 0.5 V, f = 1 MHz, $V_{\rm CB}$ = 0 ,					
collector grounded					
Minimum noise figure	NF _{min}	-	0.95	-	dB
$I_{\rm C}$ = 2 mA, $V_{\rm CE}$ = 2 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
<i>f</i> = 1.8 GHz					
Power gain, maximum stable ¹⁾	G _{ms}	-	22.5	-	dB
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 2 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$, $Z_{\rm L}$ = $Z_{\rm Lopt}$,					
<i>f</i> = 1.8 GHz					
Insertion power gain	S ₂₁ ²	-	20.5	-	
V _{CE} = 2 V, <i>I</i> _C = 20 mA, <i>f</i> = 1.8 GHz,					
$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$					
Third order intercept point at output	IP3	-	23.5	-	dBm
V _{CE} = 2 V, <i>I</i> _C = 20 mA, <i>f</i> = 1.8 GHz,					
$Z_{\rm S} = Z_{\rm Sopt,} Z_{\rm L} = Z_{\rm Lopt}$					
1dB compression point	P _{-1dB}	-	10.5	-]
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 2 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$, $Z_{\rm L}$ = $Z_{\rm Lopt}$,					
<i>f</i> = 1.8 GHz					

Electrical Characteristics at T_A = 25 °C, unless otherwise specified

 ${}^{1}G_{\rm ms} = |S_{21} / S_{12}|$



Total power dissipation $P_{tot} = f(T_S)$

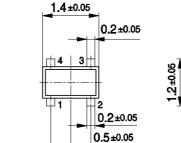




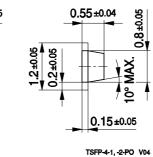
BFP520F

Package Outline

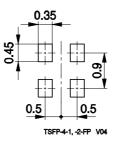




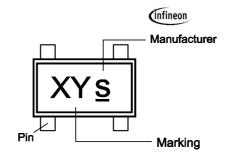
0.5±0.05



Foot Print

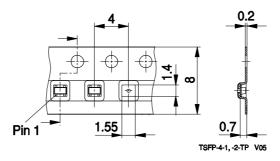


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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